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1. (Amended) A resin composition used for fabricating an interlayer dielectric of a printed wiring board, wherein said composition comprises; a) an epoxy based resin; b) an epoxy resin curing agent containing 5 to 25% by weight nitrogen; c) maleimide compounds having thermosetting properties; d) polymers having crosslinkable functional groups within a molecule; and e) a crosslinker, which is added if necessary, wherein said resin composition is free of halogen.

2. (Amended) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 1, wherein said epoxy based resin comprises epoxy resins having two or more glycidyl groups per molecule, and said epoxy resin curing agent comprises a phenol novolak epoxy resin curing agent containing triazine rings within a molecule.

3. (Amended) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 1, wherein said epoxy based resin is selected from the group consisting of bisphenol A epoxy resin, bisphenol F epoxy resin, novolak epoxy resin, cresol novolak epoxy resin, glycidylamine epoxy resin, and combinations thereof.

4. (Twice Amended) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 1, wherein said polymers having crosslinkable functional groups are selected from the group consisting of polyether sulfone resin having a

terminal hydroxyl group, polyvinyl acetal resin having repeated hydroxyl groups, phenoxy resin, and combinations thereof.

5. (Twice Amended) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 1, wherein said epoxy resin curing agent is selected from the group consisting of melamine, benzoguanamine, a compound obtained from a condensation reaction of phenols and formaldehydes; and combinations thereof.

6. (Twice Amended) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 1, wherein said maleimide compounds are selected from the group consisting of N,N'-(4,4-diphenylmethane)bismaleimide; bis(3-ethyl-5-methyl-4-maleimidephenyl)methane; 2,2-bis[4-(4-maleimidephenoxy)phenyl]propane; thermosetting maleimide compounds obtained from Michael addition reaction of these maleimide compounds and polyamines; and combinations thereof.

7. (Twice Amended) A method for producing a resin composition used for fabricating an interlayer dielectric of the printed wiring board, wherein said resin composition is added to and dissolved in the solvent to a solids content of 40 to 50 % by weight, wherein 100 parts of said resin composition comprises: 20 to 70 parts by weight of an epoxy based resin; 10 to 50 parts by weight of maleimide compounds having thermosetting properties; 5 to 30 parts by weight of polymers having crosslinkable functional groups within a molecule; and balance being a

crosslinker added as necessary and a phenol novolak epoxy resin curing agent containing triazine rings within a molecule.

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8. (Amended) A method for producing the resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 7, wherein the solvent is a mixed solvent of N-methylpyrrolidone and methyl ethyl ketone, the mixing weight ratio of N-methylpyrrolidone/methyl ethyl ketone being in a range of 50/50 to 40/60.